

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6122xxxxMR-G

Typical Mass: 16 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.454	Silicon	28400	7440-21-3
		- Arsenic	2	7440-38-2
Leadframe	5.503	Copper	343900	7440-50-8
		Tin	1400	7440-31-5
		Zinc	1300	7440-66-6
		Chromium	1500	7440-47-3
		Silver	20300	7440-22-4
		Die attach	0.049	Silver
Epoxy	600	—		
Bonding wire	0.050	Gold	3100	7440-57-5
Resin	7.472	Silica	467000	60676-86-0
		Epoxy Resin	44400	—
		Phenol Resin	37300	—
		Metal Hydroxide	26600	—
Plating	0.340	Tin	21300	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."